

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A method comprising:
 fabricating a die having imaging circuitry;
 fabricating a lid having a transparent region and support regions, the support regions having a predetermined height, the fabrication of the lid comprising:
 applying a photo-sensitive adhesive layer to a transparent plate; and
 patterning the photo-sensitive adhesive layer to form the transparent region and the support regions; and
 mounting the lid directly onto the die so that transparent region generally cover the imaging circuitry on the die but is separated from the imaging circuitry on the die by a gap having a dimension substantially equal to the predetermined height of the support regions of the lid.
2. (Original) The method of claim 1, wherein the patterning of the photo-sensitive adhesive layer is performed using photo-lithography.
3. (Original) The method of claim 1, further comprising the fabrication of a plurality of the lids by patterning the photo-sensitive adhesive layer applied to the transparent plate to form a plurality of transparent regions and corresponding support regions on the transparent plate.
4. (Original) The method of claim 1, further comprising scribing the patterned transparent plate to singulate the lids.
5. (original) The method of claim 1, further comprising encapsulating the die with the lid mounted thereon into a package.

6. (Original) The method of claim 5, wherein the package is a Tape Automated Bond (TAB) package.
7. (Original) The method of claim 5, wherein the encapsulation further comprises:
electrically coupling one or more leads to one or more contact bumps on the die; and
providing insulation around the leads.
8. (Original) The method of claim 5, wherein the encapsulation further comprises encapsulating the package in a packaging material.
9. (Original) The method of claim 7, further comprising electrically coupling one or more solder balls to the one or more leads respectively.
10. (Original) The method of claim 9, wherein the electrically coupling the one or more solder balls to the one or more leads further comprises forming electrically conductive vias in a packaging material formed between the leads and the solder balls respectively.
11. - 26 (Canceled)